

naturally adaptive.



PIEZO JET

VJV

HIGH-SPEED

For a wide range of applications, special for adhesives

Viscosity: low-high

Max Frequency:
2'000'000 dots/h
BGA Jet-on-the-Fly:
780'000 dots/h
BGA Stop & Jet:
177'000 dots/h

SHOCKWAVE JET

VDST

HIGH-SPEED

Special for solder paste

Viscosity: very high

Max Frequency:
1'100'000 dots/h
BGA Jet-on-the-Fly:
665'000 dots/h
Average Board Speed:
350'000 dots/h

VOLUME

VVD

MEDIUM SPEED

For sealing, gasketing, dam & fill applications, small to high volumes

Viscosity: low-high

26'000 dots/h
(BGA Pattern*)

MICRO SCREW

VSR

LOW/MEDIUM SPEED

For all adhesives & solder paste, dam applications

Viscosity: medium

30'000 dots/h
(BGA Pattern*)

TIME PRESSURE

VTP

MEDIUM SPEED

For simple glue & solder paste, fill applications, mid to high volumes

Viscosity: medium

38'000 dots/h
(BGA Pattern*)

naturally adaptive.

	UNDERFILL	GLOBE TOP	ENCAPSULATION	STAKING	DAM & FILL	3D DISPENSING	DISPENSING ON FOIL	SOLDER PASTE	SILVER EPOXY	UV ADHESIVE	SMD ADHESIVE	FLUX
 TIME PRESSURE		●	●		●	●	●	●	●		●	
 SCREW	●	●	●		●	●	●	●	●	●	●	
 VOLUME	●	●		●	●	●		●			●	
 PIEZO JET	●	●	●				●		●	●	●	●
 SHOCKWAVE JET								●				

● Strong ● Mid ● Low - Level of recommendation
Depending on application, other recommendation possible.
Medium, substrate, volume & speed, precision & repeatability needs.